

04-12-2006

RECORD

103216803
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Byung-Jun SONG

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) March 1, 2006

- ☒ Assignment ☐ Merger
- ☐ Security Agreement ☐ Change of Name
- ☐ Joint Research Agreement
- ☐ Government Interest Assignment
- ☐ Executive Order 9424, Confirmatory License
- ☐ Other _____

2. Name and address of receiving party(ies)

Name: Seoul Laser Dieboard System Co., Ltd.

Internal Address: _____

Street Address: 13110 Sunstone PointeCity: San DiegoState: CaliforniaCountry: USA Zip: 92130Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No (s)

☐ This document is being filed together with a new application.

B. Patent No.(s)

5,787,750

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Kyong Chan Lim

Internal Address: _____

Street Address: 13110 Sunstone PointeCity: San DiegoState: California Zip: 92130Phone Number: (858) 259-9467

Fax Number: _____

Email Address: kclimok@hotmail.com6. Total number of applications and patents involved: 17. Total fee (37 CFR 1.21(h) & 3.41) \$ 40

- ☐ Authorized to be charged by credit card
- ☐ Authorized to be charged to deposit account
- ☒ Enclosed
- ☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature:

Signature

March 23, 2006

Date

Kyong Chan Lim
Name of Person SigningTotal number of pages including cover
sheet, attachments, and documents

3

2. Name and address of additional receiving party

Name: Seoul Laser Dieboard System Co., Ltd.
Street Address: 1029-30 Hogae-dong, Dongan-ku
City: Anyang City
State: Kyunggido
Country: KOREA

ASSIGNMENT

U.S. Patent No.: 5,787,750
Title: FOLDING SYSTEM FOR A CUTTING BLADE
Issued: August 4, 1998

WHEREAS, I, Byung-Jun Song (hereinafter referred to as "ASSIGNOR"), owner of the entire right, title, and interest in U.S. Letters Patent No. 5,787,750, residing at 1029-30 Hokye-dong, Anyangi-si, Dongan-ky, Kyungki-do, Korea, is desirous of transferring all interest in, to and under said U.S. Letters Patent to Seoul Laser Dieboard System Co., Ltd. (hereinafter referred to as "ASSIGNEE 1"), a corporation operating in California, located at 13110 Sunstone Pointe, San Diego California 92130, and to Seoul Laser Dieboard System Co., Ltd. (hereinafter referred to as "ASSIGNEE 2"), a Korean Company, located at 1029-30 Hogae-dong, Dongan-ku, Anyang City, Kyunggido, Korea. ASSIGNEE 1 and ASSIGNEE 2 (collectively referred to as "ASSIGNEES") are desirous of acquiring all interest in, to and under said U.S. Letters Patent.

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, Byung-Jun Song, the ASSIGNOR, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said U.S. Letters Patent, including any divisions and continuations deriving from said U.S. Letters Patent, and in and to any and all patents deriving from said U.S. Letters Patent in countries foreign to the United States.

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment is executed on the dates indicated below.

Byung-Jun SONG

Name of the ASSIGNOR



Signature of the ASSIGNOR

Mar 01 '06

Date of Assignment